



## Message from the Editor

Here, we offer the fourth volume of Transactions of The Japan Institute of Electronics Packaging (Trans. JIEP). I believe that Trans. JIEP is firmly established as a technical journal in microelectronics packaging technologies. Again this year, I will make a most cordial acknowledgment to all the persons involved in publishing Trans. JIEP, including authors, reviewers/referees, editorial committee members, society members, and the secretariat. This year's volume contains excellent and attractive papers in the field of 3-D packaging, thermal management (cooling and heat dissipation), high-frequency signal transmission, new materials/materials engineering, and so on. I think that there is no doubt that these papers will yield valuable information to you.

I know that there have been many superior papers which were presented in various JIEP Conferences/Symposiums, technical meetings, and so on. I hope that you will submit these papers and will publish your important and remarkable achievements through Trans. JIEP. This year, we had heavy losses due to natural disasters, so I have a keenly renewed sense of the importance of pursuing the “safety” and “security” of all the industrial technologies including microelectronics packaging technologies. We earnestly expect to receive papers written with a view to safety and security.

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